

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

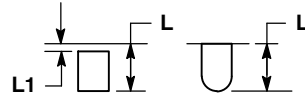
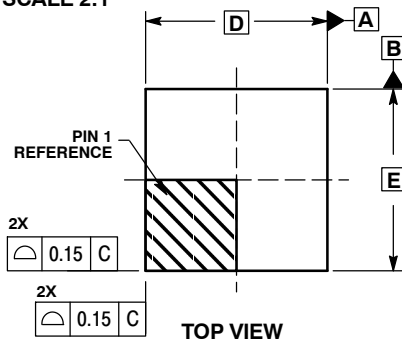
ON Semiconductor®



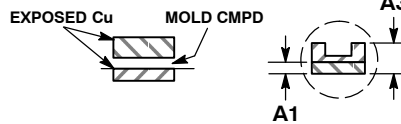
1
SCALE 2:1

WDFN6 3x3, 0.95P
CASE 511AP-01
ISSUE O

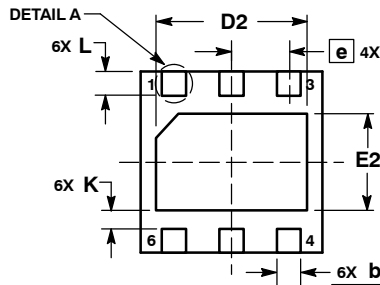
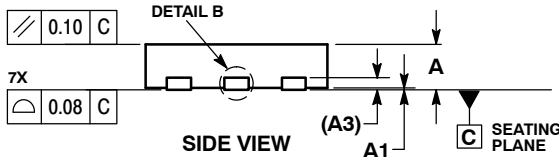
DATE 12 MAY 2009



DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS



DETAIL B
ALTERNATE
CONSTRUCTIONS

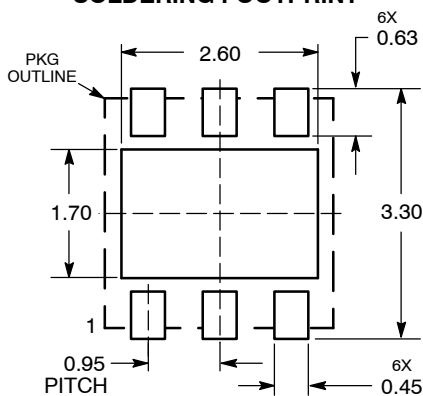


BOTTOM VIEW

⊕	0.10	C	A	B
	0.05	C		

NOTE 3

SOLDERING FOOTPRINT*



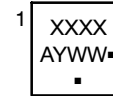
DIMENSIONS: MILLIMETERS

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.35	0.45
D	3.00	BSC
D2	2.40	2.60
E	3.00	BSC
E2	1.50	1.70
e	0.95	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)


*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WDFN6 3X3, 0.95P, SINGLE FLAG	PAGE 1 OF 2



ISSUE	REVISION	DATE
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